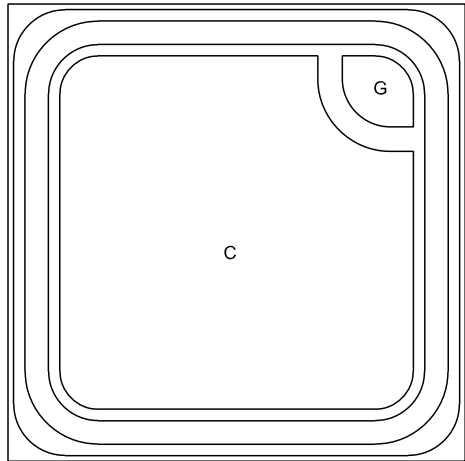


PROCESS DETAILS

Process	Glass Passivated Mesa
Die Size	150 x 150 MILS
Die Thickness	8.7 MILS
Cathode Bonding Pad Area	117 x 84 MILS
Gate Bonding Pad Area	24 x 24 MILS
Top Side Metalization	Al - 45,000Å
Back Side Metalization	Al/Mo/Ni/Ag - 32,000Å

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GEOMETRY



GROSS DIER PER 4 INCH WAFER

466

PRINCIPAL DEVICE TYPES

CS220-25M Series
CSDD-25M Series

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